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		$\frac{1}{2}$					
-	H1 1902C NY PMS 440 0025 PH	2					
	PCB: PMP7900 REV	A PCB LOGO					
	PMP7900 REVA	LOGO Texas Instruments					
		$\overset{H8}{\frown}$					
	H3	4 Y PMS 440 0025 PH					
	LBL1						
	Size: 0.65" x 0.20 "						
	ZZ1 Label Assembly Note This Assembly Note is for PCB labels only						
	ZZ2 Assembly Note						
	Assembly Note These assemblies are ESD sensitive, ESD precautio ZZ3 Assembly Note						
	ZZ4	and all contaminants. Use of no clean flux is not acceptable.					
	These assemblies must comply with workmanship s	tandards IPC-A-610 Class 2., unless otherwise specified.					
					Designed for: Public Re Project Title: LM5000 F Number: PMP7932 Rev: E1 Sheet Title: the StAL Boy: Not in version control. Accomptly Variant: 001	elease Mod. Date: 1/20/2015 Flyback Industrial Bias Supply	TEXAS INSTRUMENTS
		Texas Instruments and/or its licens warrant that this design will meet the licensors do not warrant that the d	sors do not warrant the accuracy or completeness of this specification or he specifications, will be suitable for your application or fit for any particul esign is production worthy. You should completely validate and test your	any information contained therein. Texas Instruments and/or its licensors do no ar purpose, or will operate in an implementation. Texas Instruments and/or its design implementation to confirm the system functionality for your application.	INITIAL POLICY INITIAL POLICY It SVN Rev: Not in version control Assembly Variant: 001 Drawn By: File: PMP7932_Hardwa Engineer: David Baba Contact: http://www.ti.c	Sheet:2 of 2 are_ANSI-B.SchDoc Size: B com/support	INSTRUMENTS http://www.ti.com © Texas Instruments 2014
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